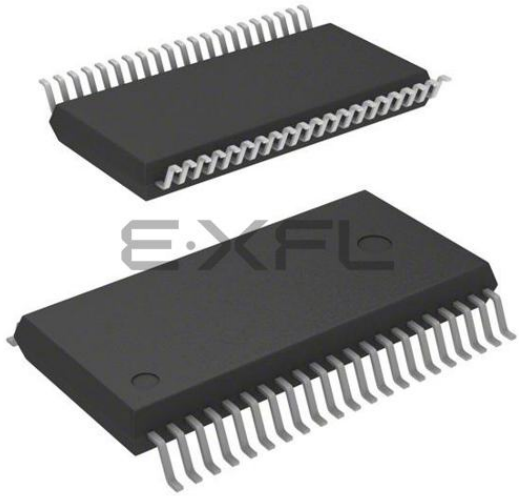
Renesas Electronics America Inc - M30263F8AFP#U5A Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	M16C/60
Core Size	16-Bit
Speed	24MHz
Connectivity	I²C, IEBus, SIO, UART/USART
Peripherals	DMA, PWM, Voltage Detect, WDT
Number of I/O	33
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	42-SOP (0.330", 8.40mm Width)
Supplier Device Package	42-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/m30263f8afp-u5a

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1. Overview

The M16C/26A Group (M16C/26A, M16C/26B, M16C/26T) is a single-chip control MCU, fabricated using high-performance silicon gate CMOS technology, embedding the M16C/60 Series CPU core. The M16C/26A Group (M16C/26A, M16C/26B, M16C/26T) is housed in 42-pin and 48-pin plastic molded packages. With a 1M byte address space, this MCU combines advanced instruction manipulation capabilities to process complex instructions by less bytes and execute instructions at higher speed. The M16C/26A Group (M16C/26A, M16C/26B, M16C/26T) has a multiplier and DMAC adequate for office automation, communication devices and industrial equipment, and other high-speed processing applications.

1.1 Applications

Audio, cameras, office/communications/portable/ equipment, air-conditioning equipment, home appliances, etc.

1.2 Performance Outline

Table 1.1 and **1.2** outline performance overview of the M16C/26A Group (M16C/26A, M16C/26B, M16C/26T).

Table 1.1. M16C/26A Group(M16C/26A, M16C/26B, M16C/26T) Performance (48-Pin Package)

Item		Specification
CPU	Basic instructions	91 instructions
	Minimun instruction execution time	41.7 ns (f(BCLK) = 24MHz(4), Vcc = 4.2 to 5.5 V) (M16C/26B) 50 ns (f(BCLK) = 20MHz, Vcc = 3.0 to 5.5 V) (M16C/26A, M16C/26B, M16C/26T(T-ver.)) 100 ns (f(BCLK) = 10MHz, Vcc = 2.7 to 5.5 V) (M16C/26A , M16C/26B) 50 ns (f(BCLK) = 20MHz, Vcc = 4.2 to 5.5 V -40 to 105°C) (M16C/26T(V-ver.)) 62.5 ns (f(BCLK) = 16MHz, Vcc = 4.2 to 5.5 V -40 to 125°C) (M16C/26T(V-ver.))
	Operating mode	Single-chip mode
	Address space	1 Mbyte
	Memory capacity	See **1.4 Product Information**
Peripheral Function	I/O ports	39 I/O pins
	Multifunction timers	TimerA:16 bits x 5 channels, TimerB:16 bits x 3 channels Three-phase motor control timer
	Serial I/O	2 channels (UART, clock synchronous serial I/O) 1 channel (UART, clock synchronous, I2C bus(1) , or IEBus(2))
	A/D converter	10 bit A/D Converter : 1 circuit, 12 channels
	DMAC	2 channels
	CRC calcuration circuit	1 circuit (CRC-CCITT and CRC-16) with MSB/LSB selectable
	Watchdog timer	15 bits x 1 channel (with prescaler)
	Interrupts	20 internal and 8 external sources, 4 software sources, Interrupt priority level: 7
	Clock generation circuit	4 circuits Main clock oscillation circuit(*), Sub-clock oscillation circuit(*) On-chip oscillator, PLL frequency synthesizer (*)Equipped with a built-in feedback resister.
	Oscillation stop detection	Main clock oscillation stop, re-oscillation detection function
	Voltage detection circuit	On-chip (M16C/26A, M16C/26B), not on-chip (M16C/26T)
Electrical Characteristics	Power supply voltage	Vcc = 4.2 to 5.5 V (f(BCLK) = 24 MHz)(4) (M16C/26B) Vcc = 3.0 to 5.5 V (f(BCLK) = 20 MHz) (M16C/26A, M16C/26B) Vcc = 2.7 to 5.5 V (f(BCLK) = 10 MHz) Vcc = 3.0 to 5.5 V (M16C/26T(T-ver.)) Vcc = 4.2 to 5.5 V (M16C/26T(V-ver.))
	Power consumption	16 mA (Vcc = 5 V, f(BCLK) = 20 MHz) 25 µA (f(XCIN) = 32 KHz on RAM) 3 µA (Vcc = 3 V, f(XCIN) = 32 KHz, in wait mode) 0.7 µA (Vcc = 3 V, in stop mode)
Flash Memory Version	Programming /erasure voltage	2.7 to 5.5 V (M16C/26A, M16C/26B) 3.0 to 5.5 V (M16C/26T(T-ver.)) 4.2 to 5.5 V (M16C/26T(V-ver.))
	Programming /erasure endurance	100 times (all area) or 1,000 times (block 0 to 3) / 10,000 times (block A, block B)(3)
Operating Ambient Temperature		-20 to 85°C / -40 to 85°C (3) (M16C/26A , M16C/26B) -40 to 85°C (M16C/26T(T-ver.)) -40 to 105°C / -40 to 125°C (M16C/26T(V-ver.))
Package		48-pin plastic molded QFP

NOTES:
1. I2C bus is a trademark of Koninklijke Philips Electronics N. V.
2. IEBus is a trademark of NEC Electronics Corporation.
3. See **Table 1.7 Product Code** for the program and erase endurance, and operating ambient temperature.
4. The PLL frequency synthesizer is used to run the M16C/26B at f(BCLK) = 24 MHz.

Table 1.2. Performance outline of M16C/26A group (M16C/26A, M16C/26B) (42-pin device)

	Item	Performance
CPU	Basic instructions	91 instructions
	Minimun instruction execution time	41.7 ns (f(BCLK) = 24 MHz (4), VCC = 4.2 to 5.5 V (M16C/26B) 50 ns (f(BCLK) = 20 MHz, Vcc = 3.0 to 5.5 V) (M16C/26A, M16C/26B) 100 ns (f(BCLK) = 10 MHz, Vcc = 2.7 to 5.5 V) (M16C/26A, M16C/26B)
	Operation mode	Single-chip mode
	Address space	1M byte
	Memory capacity	See **1.4 Product Information**
Peripheral function	Port	33 I/O pins
	Multifunction timer	Timer A: 16 bits x 5 channels, Timer B: 16 bits x 3 channels Three-phase motor control timer
	Serial I/O	1 channel (UART, clock synchronous serial I/O) 1 channel (UART, clock synchronous, I^2C bus(1) , or IEBus(2))
	A/D converter	10 bit A/D converter: 1 circuit, 10 channels
	DMAC	2 channels
	CRC calcuration circuit	1 circuits (CRC-CCITT and CRC-16) with MSB/LSB selectable
	Watchdog timer	15 bits x 1 channel (with prescaler)
	Interrupt	18 internal and 8 external sources, 4 software sources, Interrupt priority level: 7
	Clock generation circuit	4 circuits Main clock(*), Sub-clock(*) On-chip oscillator, PLL frequency synthesizer (*)Equipped with a built-in feedback resister.
	Oscillation stop detection	Main clock oscillation stop, re-oscillation detection function
	Voltage detection circuit	On-chip
Electrical Characteristics	Supply voltage	Vcc = 4.2 to 5.5 V (f(BCLK) = 24 MHz)(4) (M16C/26B) Vcc = 3.0 to 5.5 V (f(BCLK) = 20 MHz) (M16C/26A, M16C/26B) Vcc = 2.7 to 5.5 V (f(BCLK) = 10 MHz)
	Power Consumption	16 mA (Vcc = 5 V, f(BCLK) = 20 MHz) 25 μA (f(XCIN) = 32 KHz on RAM) 3 μA (Vcc = 3 V, f(XCIN) = 32 KHz, in wait mode) 0.7 μA (Vcc = 3 V, in stop mode)
Flash memory	Programming/erasure voltage	2.7 to 5.5 V
	Programming/erasure endurance	100 times (all area) or 1,000 times (block 0 to 3) / 10,000 times (block A, block B)(3)
Operating Ambient Temperature		-20 to 85°C / -40 to 85°C (3)
Package		42-pin plastic molded SSOP

NOTES:
1. I^2C bus is a trademark of Koninklijke Philips Electronics N. V.
2. IEBus is a trademark of NEC Electronics Corporation.
3. See **Table 1.7 Product Code** for the program and erase endurance, and operating ambient temperature.
4. The PLL frequency synthesizer is used to run the M16C/26B at f(BCLK) = 24 MHz.

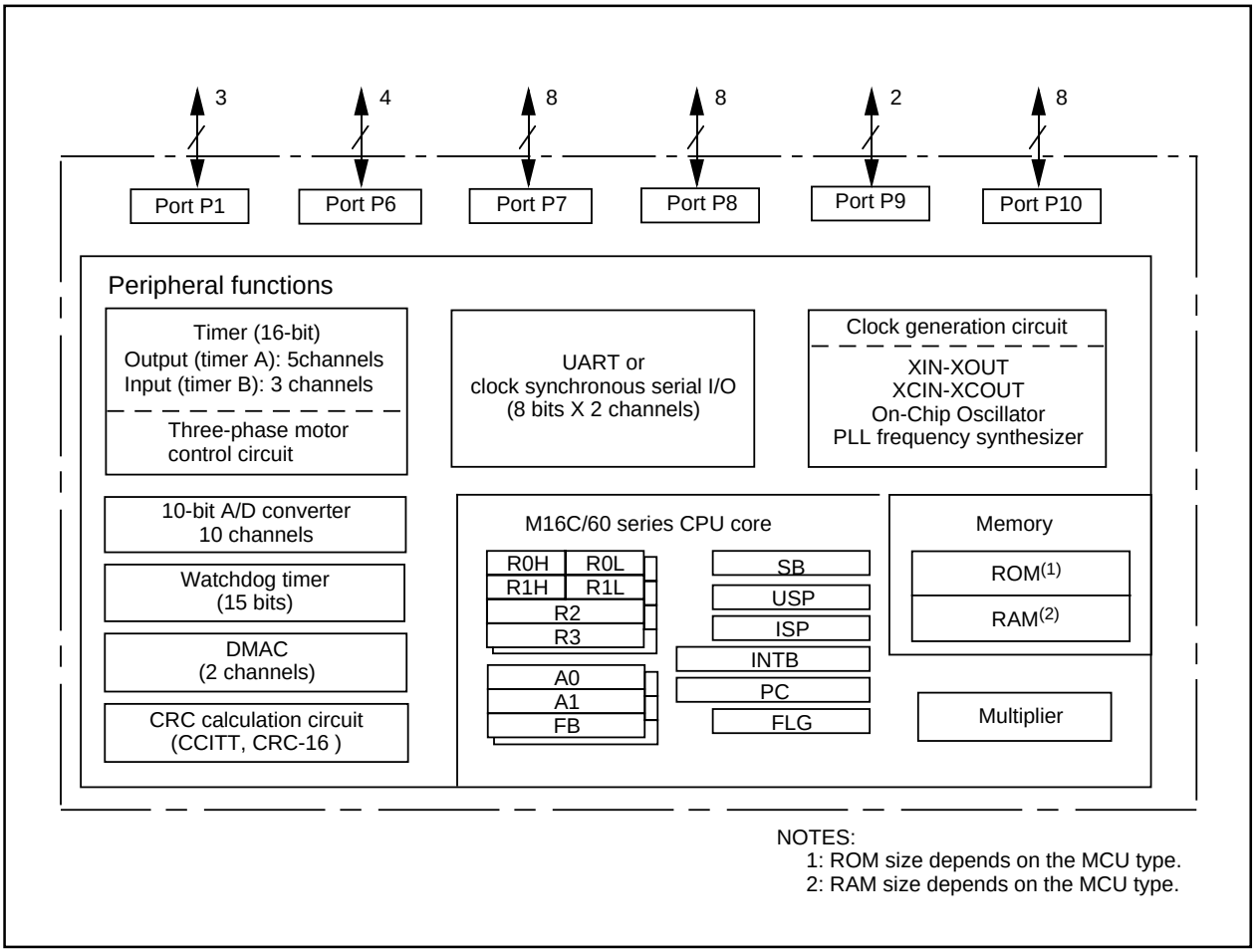


Figure 1.2 Block Diagram(42-pin Package)

1.4 Product List

Tables 1.3 to **1.6** lists product information, **Figure 1.3** shows a product numbering system, **Table 1.7** lists the product code, and **Figure 1.4** shows the marking.

Table 1.3 M16C/26A **Current as of Jul., 2006**

Type Number		ROM Capacity	RAM Capacity	Package Type	Remarks	Product Code
M30260F3AGP	(N)	24K + 4K	1K	PLQP0048KB-A (48P6Q-A)	Flash memory	U3, U5, U7, U9
M30260F6AGP	(N)	48K + 4K	2K			
M30260F8AGP	(N)	64K + 4K	2K			
M30263F3AFP	(N)	24K + 4K	1K	PRSP0042GA-B (42P2R)		U5, U9
M30263F6AFP	(N)	48K + 4K	2K			
M30263F8AFP	(N)	64K + 4K	2K			
M30260M3A-XXXGP	(N)	24K	1K	PLQP0048KB-A (48P6Q-A)	Mask ROM	U3, U5
M30260M6A-XXXGP	(N)	48K	2K			
M30260M8A-XXXGP	(N)	64K	2K			
M30263M3A-XXXFP	(N)	24K	1K	PRSP0042GA-B (42P2R)		U5
M30263M6A-XXXFP	(N)	48K	2K			
M30263M8A-XXXFP	(N)	64K	2K			

(N): New

Table 1.4 M16C/26B **Current as of Jul., 2006**

Type Number		ROM Capacity	RAM Capacity	Package Type	Remarks	Product Code
M30260F8BGP	(D)	64K + 4K	2K	PLQP0048KB-A (48P6Q-A)	Flash memory	U7
M30263F8BFP	(D)	64K + 4K	2K	PRSP0042GA-B (42P2R)		U9

(D): Under development

Table 1.5 M16C/26T T-ver. **Current as of Jul., 2006**

Type Number	ROM Capacity	RAM Capacity	Package Type	Remarks	Product Code
M30260F3TGP	24K + 4K	1K	PLQP0048KB-A (48P6Q-A)	Flash memory	U3, U7
M30260F6TGP	48K + 4K	2K			
M30260F8TGP	64K + 4K	2K			

NOTE:
1. Please contact Renesas Technolog Corp. for details on Mask ROM version.

Table 1.6 M16C/26T V-ver. **Current as of Jul., 2006**

Type Number	ROM Capacity	RAM Capacity	Package	Remarks	Product Code
M30260F3VGP	24K + 4K	1K	PLQP0048KB-A (48P6Q-A)	Flash memory	U3, U7
M30260F6VGP	48K + 4K	2K			
M30260F8VGP	64K + 4K	2K			

NOTE:
1. Please contact Renesas Technolog Corp. for details on Mask ROM version.

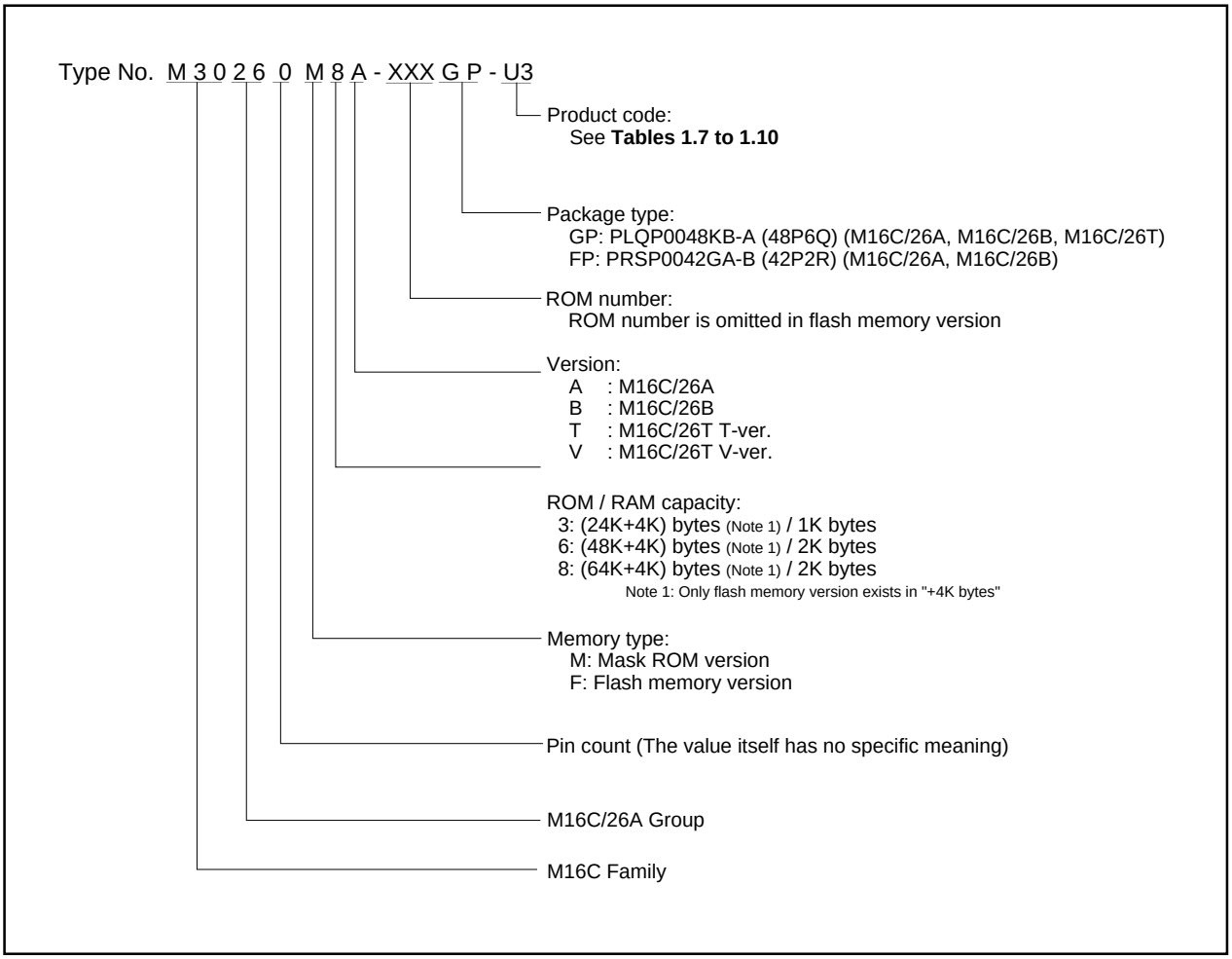


Figure 1.3 Product Numbering System

Table 1.7 Product Code (Flash Memory Version) - M16C/26A, M16C/26B

Product Code	Package	Internal ROM (User Program Space)		Internal ROM (Data Space)		Operating Ambient Temperature
		Program and Erase Endurance	Temperature Range	Program and Erase Endurance	Temperature Range	
U3	Lead free	100	0 to 60°C	100	0 to 60°C	-40 to 85°C
U5						-20 to 85°C
U7		1,000		10,000	-40 to 85°C	-40 to 85°C
U9					-20 to 85°C	-20 to 85°C

Table 1.8 Product Code (Mask ROM Version - M16C/26A)

Product Code	Package	Operating Ambient Temperature
U3	Lead free	-40°C to 85°C
U5		-20°C to 85°C

NOTE:

1. The lead contained products, D3, D5, D7, and D9 are put together with U3, U5, U7, and U9 respectively. Lead-free products can be mounted by both conventional Sn-Pb paste and Lead-free paste (Sn-Ag-Cu plating).

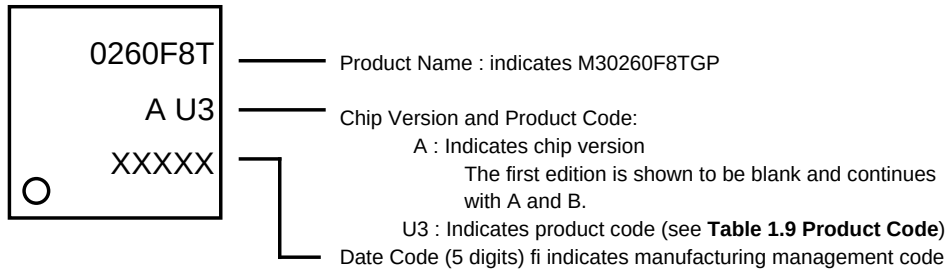
Table 1.9 Product Code (Flash Memory Version) - M16C/26T T-ver.

Product Code	Package	Internal ROM (User Program Space)		Internal ROM (Data Space)		Operating Ambient Temerature
		Programming and erasure endurance	Temperature range	Programming and erasure endurance	Temperature range	
U3	Lead free	100	0°C to 60°C	100	-40°C to 85°C	-40°C to 85°C
U7		1,000		10,000		

Table 1.10 Product Code (Flash Memory Version) - M16C/26T V-ver.

Product Code	Package	Internal ROM (User Program Space)		Internal ROM (Data Space)		Operating Ambient Temerature
		Programming and erasure endurance	Temperature range	Programming and erasure endurance	Temperature range	
U3	Lead free	100	0°C to 60°C	100	-40°C to 125°C	-40°C to 125°C
U7		1,000		10,000		

(1) Flash memory version, PLQP0048KB-A (48P6Q), M16C/26T T-ver.



(2) Flash memory version, PLQP0048KB-A (48P6Q), M16C/26T V-ver.

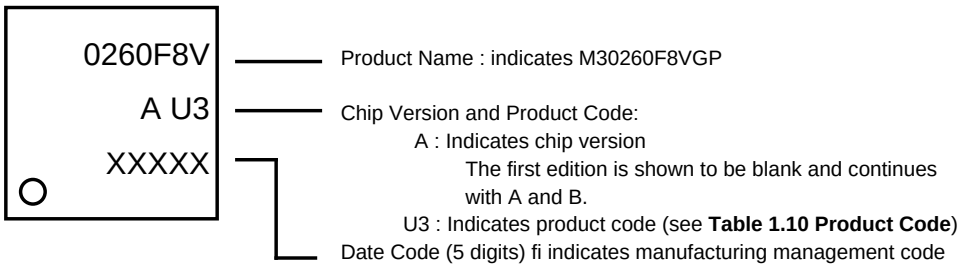


Figure 1.5 Marking Diagram (M16C/26T)

1.5 Pin Assignments

Figures 1.6 and **1.7** show the Pin Assignments (top view).

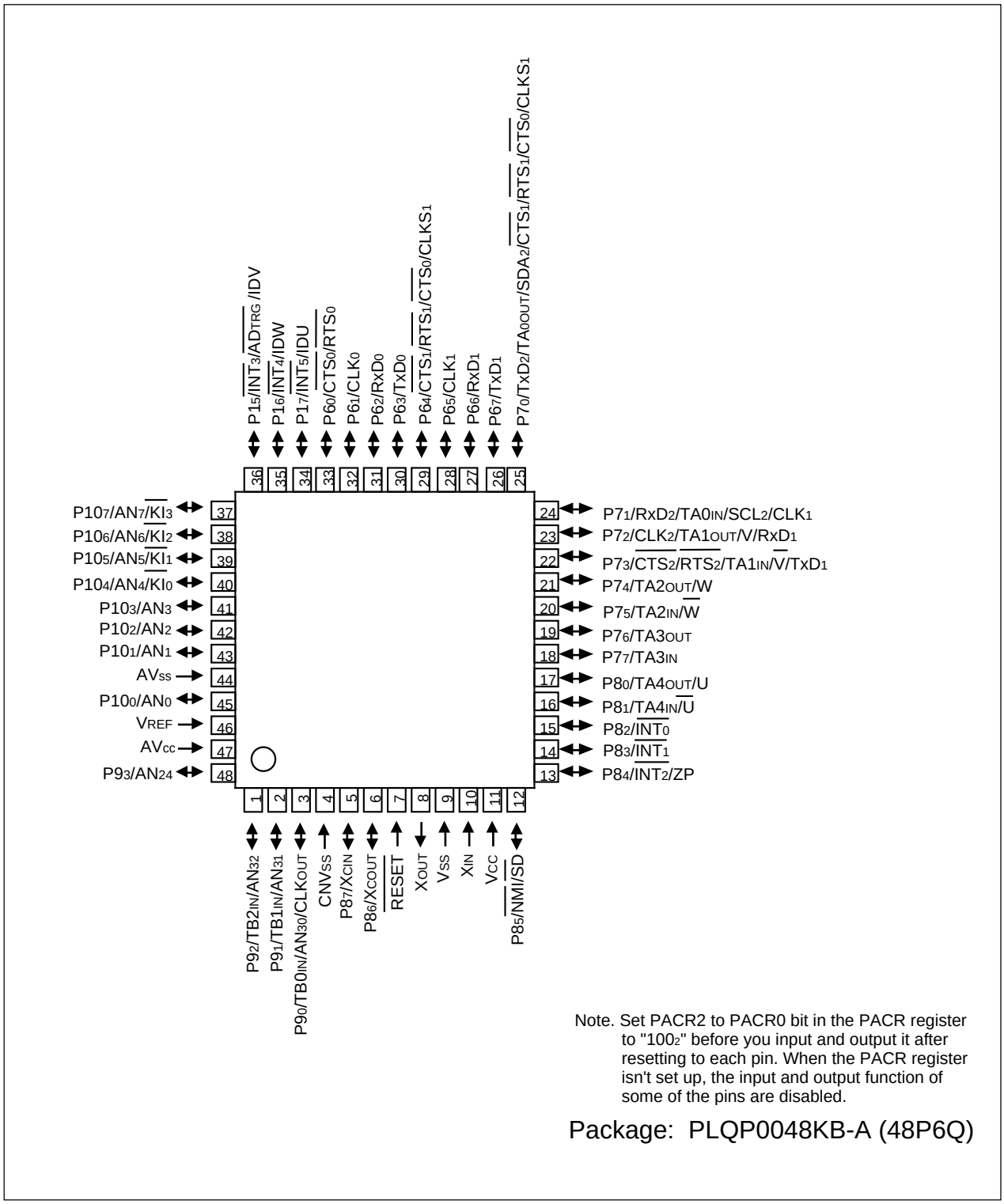


Figure 1.6 Pin Assignment for 48-Pin Package (Top View)

Table 1.12 Pin Characteristics for 42-Pin Package

Pin No.	Control Pin	Port	Interrupt Pin	Timer Pin	UART Pin	Analog Pin
1	AVss					
2		P10$_0$				AN$_0$
3	VREF					
4	AVCC					
5		P9$_1$		TB$_{1IN}$		AN3$_1$
6		P9$_0$		TB$_{0IN}$	CLK$_{OUT}$	AN3$_0$
7	CNVss					
8	XCIN	P8$_7$				
9	XCOUT	P8$_6$				
10	$\overline{\text{RESET}}$					
11	XOUT					
12	Vss					
13	XIN					
14	VCC					
15		P8$_5$	$\overline{\text{NMI}}$	$\overline{\text{SD}}$		
16		P8$_4$	$\overline{\text{INT}}_2$	ZP		
17		P8$_3$	$\overline{\text{INT}}_1$			
18		P8$_2$	$\overline{\text{INT}}_0$			
19		P8$_1$		TA$_{4IN}$ / $\overline{\text{U}}$		
20		P8$_0$		TA$_{4OUT}$ / U		
21		P7$_7$		TA$_{3IN}$		
22		P7$_6$		TA$_{3OUT}$		
23		P7$_5$		TA$_{2IN}$ / $\overline{\text{W}}$		
24		P7$_4$		TA$_{2OUT}$ / W		
25		P7$_3$		TA$_{1IN}$ / $\overline{\text{V}}$	$\overline{\text{CTS}}_2$ / $\overline{\text{RTS}}_2$ / TxD$_1$	
26		P7$_2$		TA$_{1OUT}$ / V	CLK$_2$ / RxD$_1$	
27		P7$_1$		TA$_{0IN}$	RxD$_2$ / SCL$_2$ / CLK$_1$	
28		P7$_0$		TA$_{0OUT}$	TxD$_2$ / SDA$_2$ / $\overline{\text{RTS}}_1$ / $\overline{\text{CTS}}_1$ / $\overline{\text{CTS}}_0$ / CLKS$_1$	
29		P6$_7$			TxD$_1$	
30		P6$_6$			RxD$_1$	
31		P6$_5$			CLK$_1$	
32		P6$_4$			$\overline{\text{RTS}}_1$ / $\overline{\text{CTS}}_1$/ $\overline{\text{CTS}}_0$ / CLKS$_1$	
33		P1$_7$	$\overline{\text{INT}}_5$	IDU		
34		P1$_6$	$\overline{\text{INT}}_4$	IDW		
35		P1$_5$	$\overline{\text{INT}}_3$	IDV		$\overline{\text{ADTRG}}$
36		P10$_7$	$\overline{\text{KI}}_3$			AN$_7$
37		P10$_6$	$\overline{\text{KI}}_2$			AN$_6$
38		P10$_5$	$\overline{\text{KI}}_1$			AN$_5$
39		P10$_4$	$\overline{\text{KI}}_0$			AN$_4$
40		P10$_3$				AN$_3$
41		P10$_2$				AN$_2$
42		P10$_1$				AN$_1$

1.6 Pin Description

Table 1.13 Pin Description (48-Pin and 42-Pin Packages)

Classification	Pin Name	I/O Type	Description
Power Supply	VCC, VSS	I	Apply 0V to the Vss pin. Apply following voltage to the Vcc pin. 2.7 to 5.5 V (M16C/26A, M16C/26B), 3.0 to 5.5 V (M16C/26T T-ver.), 4.2 to 5.5 V (M16C/26T V-ver.)
Analog Power Supply	AVCC AVSS	I	Supplies power to the A/D converter. Connect the AVCC pin to VCC and the AVSS pin to VSS
Reset Input	$\overline{\text{RESET}}$	I	The MCU is in a reset state when "L" is applied to the $\overline{\text{RESET}}$ pin
CNVSS	CNVSS	I	Connect the CNVSS pin to VSS
Main Clock Input	XIN	I	I/O pins for the main clock oscillation circuit. Connect a ceramic resonator or crystal oscillator between XIN and XOUT. To apply external clock, apply it to XIN and leave XOUT open. If XIN is not used (for external oscillator or external clock), connect XIN pin to VCC and leave XOUT open
Main Clock Output	XOUT	O	
Sub Clock Input	XCIN	I	I/O pins for the sub clock oscillation circuit. Connect a crystal oscillator between XCIN and XCOUT
Sub Clock Output	XCOUT	O	
Clock Output	CLKOUT	O	Outputs the clock having the same frequency as f1, f8, f32, or fC
$\overline{\text{INT}}$ Interrupt Input	$\overline{\text{INT0}}$ to $\overline{\text{INT5}}$	I	Input pins for the $\overline{\text{INT}}$ interrupt. $\overline{\text{INT2}}$ can be used for Timer A Z-phase function
$\overline{\text{NMI}}$ Interrupt Input	$\overline{\text{NMI}}$	I	$\overline{\text{NMI}}$ interrupt input pin. $\overline{\text{NMI}}$ cannot be used as I/O port while the three-phase motor control is enabled. Apply a stable "H" to $\overline{\text{NMI}}$ after setting it's direction register to "0" when the three-phase motor control is enabled
Key Input Interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI3}}$	I	Input pins for the key input interrupt
Timer A	TA0OUT to TA4OUT	I/O	I/O pins for the timer A0 to A4
	TA0IN to TA4IN	I	Input pins for the timer A0 to A4
	ZP	I	Input pin for Z-phase
Timer B	TB0IN to TB1IN	I	Timer B0 to B1 input pins
Three-Phase Motor Control Timer Output	U, $\overline{\text{U}}$, V, $\overline{\text{V}}$, W, $\overline{\text{W}}$	O	Output pins for the three-phase motor control timer
	IDU, IDW, IDV, $\overline{\text{SD}}$	I/O	I/O pins for the three-phase motor control timer
Serial I/O	$\overline{\text{CTS1}}$ to $\overline{\text{CTS2}}$	I	Input pins to control data transmission
	$\overline{\text{RTS1}}$ to $\overline{\text{RTS2}}$	O	Output pins to control data reception
	CLK1 to CLK2	I/O	Inputs and outputs the transfer clock
	RxD1 to RxD2	I	Inputs serial data
	TxD1 to TxD2	O	Outputs serial data
	CLKS1	O	Output pin for transfer clock
Reference Voltage Input	VREF	I	Applies reference voltage to the A/D converter
A/D Converter	AN0 to AN7 AN30 to AN31	I	Analog input pins for the A/D converter
	$\overline{\text{ADTRG}}$	I	Input pin for an external A/D trigger
I/O Ports	P15 to P17	I/O	I/O ports for CMOS. Each port can be programmed for input or output under the control of the direction register. An input port can be set, by program, for a pull-up resistor available or for no pull-up resister available in 3-bit units
	P64 to P67 P70 to P77 P80 to P87 P100 to P107 P90 to P91	I/O	I/O ports for CMOS. Each port can be programmed for input or output under the control of the direction register. An input port can be set, by program, for a pull-up resistor available or for no pull-up resister available in 4-bit units

I : Input O : Output I/O : Input and output

Table 1.13 Pin Description (48-pin packages only) (Continued)

Classification	Pin Name	I/O Type	Description
Serial I/O	$\overline{CTS0}$	I	Inputs pin to control data transmission
	$\overline{RTS0}$	O	Output pin to control data reception
	CLK0	I/O	Inputs and outputs the transfer clock
	RxD0	I	Inputs serial data
	TxD0	O	Outputs serial data
Timer B	TB2IN	I	Timer B2 input pin
A/D Converter	$AN2_4$ $AN3_2$	I	Analog input pins for the A/D converter
I/O Ports	$P6_0$ to $P6_3$ $P9_2$ to $P9_3$	I/O	I/O ports for CMOS. Each port can be programmed for input or output under the control of the direction register. An input port can be set, by program, for a pull-up resistor available or for no pull-up resister available in 4-bit units

I : Input O : Output I/O : Input and output

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU registers. The register bank is comprised of seven registers (R0, R1, R2, R3, A0, A1 and FB) out of 13 registers. There are two sets of register bank.

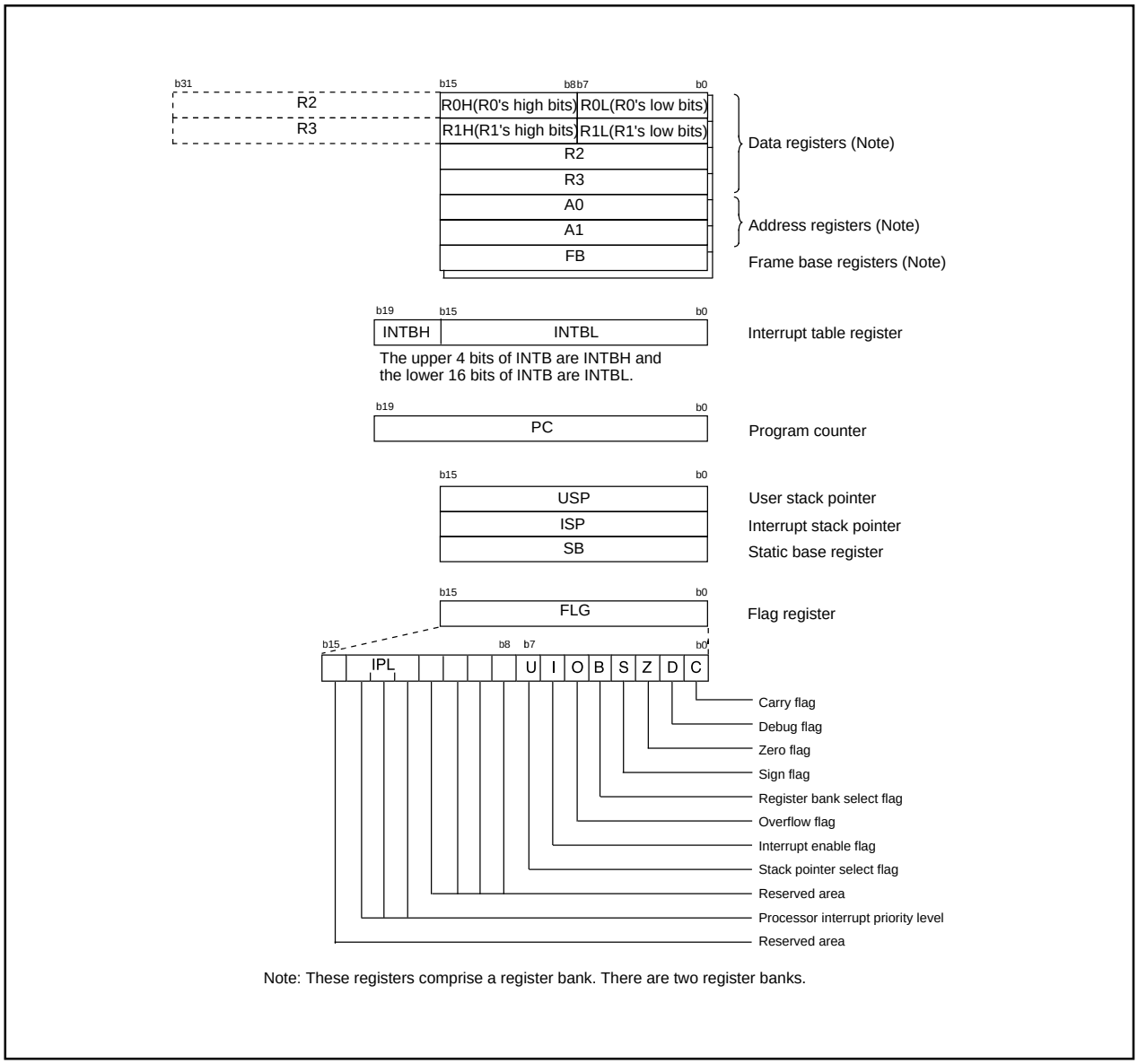


Figure 2.1. CPU Register

2.1 Data Registers (R0, R1, R2 and R3)

The R0 register consists of 16 bits, and is used mainly for transfers and arithmetic/logic operations. R1 to R3 are the same as R0.

The R0 register can be separated between high (R0H) and low (R0L) for use as two 8-bit data registers. R1H and R1L are the same as R0H and R0L. Conversely, R2 and R0 can be combined for use as a 32-bit data register (R2R0). R3R1 is the same as R2R0.

2.2 Address Registers (A0 and A1)

The register A0 consists of 16 bits, and is used for address register indirect addressing and address register relative addressing. They also are used for transfers and arithmetic/logic operations. A1 is the same as A0.

In some instructions, registers A1 and A0 can be combined for use as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is configured with 16 bits, and is used for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is configured with 20 bits, indicating the start address of an interrupt vector table.

2.5 Program Counter (PC)

PC is configured with 20 bits, indicating the address of an instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

Stack pointer (SP) comes in two types: USP and ISP, each configured with 16 bits.

Your desired type of stack pointer (USP or ISP) can be selected by the U flag of FLG.

2.7 Static Base Register (SB)

SB is configured with 16 bits, and is used for SB relative addressing.

2.8 Flag Register (FLG)

FLG consists of 11 bits, indicating the CPU status.

2.8.1 Carry Flag (C Flag)

This flag retains a carry, borrow, or shift-out bit that has occurred in the arithmetic/logic unit.

2.8.2 Debug Flag (D Flag)

The D flag is used exclusively for debugging purpose. During normal use, it must be set to 0.

2.8.3 Zero Flag (Z Flag)

This flag is set to 1 when an arithmetic operation resulted in 0; otherwise, it is 0.

2.8.4 Sign Flag (S Flag)

This flag is set to 1 when an arithmetic operation resulted in a negative value; otherwise, it is 0.

2.8.5 Register Bank Select Flag (B Flag)

Register bank 0 is selected when this flag is 0 ; register bank 1 is selected when this flag is 1.

2.8.6 Overflow Flag (O Flag)

This flag is set to 1 when the operation resulted in an overflow; otherwise, it is 0.

2.8.7 Interrupt Enable Flag (I Flag)

This flag enables a maskable interrupt.

Maskable interrupts are disabled when the I flag is 0, and are enabled when the I flag is 1.

The I flag is cleared to 0 when the interrupt request is accepted.

2.8.8 Stack Pointer Select Flag (U Flag)

ISP is selected when the U flag is 0; USP is selected when the U flag is 1.

The U flag is cleared to 0 when a hardware interrupt request is accepted or an INT instruction for software interrupt Nos. 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is configured with three bits, for specification of up to eight processor interrupt priority levels from level 0 to level 7.

If a requested interrupt has priority greater than IPL, the interrupt is enabled.

2.8.10 Reserved Area

When write to this bit, write 0. When read, its content is undefined.

3. Memory

Figure 3.1 is a memory map of the M16C/26A Group (M16C/26A, M16C/26B, M16C/26T). The M16C/26A Group provides 1-Mbyte address space addresses 00000_{16} to $FFFFF_{16}$.

The internal ROM is allocated lower address, beginning with address $FFFFF_{16}$. For example, a 64-Kbyte internal ROM area is allocated in addresses $F0000_{16}$ to $FFFFF_{16}$. The flash memory version has two sets of 2-Kbyte internal ROM area, block A and block B, for data space. These blocks are allocated addresses $F000_{16}$ to $FFFF_{16}$.

The fixed interrupt vectors are allocated addresses $FFFDC_{16}$ to $FFFFF_{16}$ and they store the start address of each interrupt routine.

The internal RAM is allocated higher addresses, beginning with address 00400_{16}. For example, a 1-Kbyte internal RAM area is allocated in addresses 00400_{16} to $007FF_{16}$. The internal RAM is used for temporarily storing data. The area is also used as stacks when subroutines are called or interrupt requests are acknowledged.

The SFR is allocated addresses 00000_{16} to $003FF_{16}$. The peripheral function control registers are allocated here. All blank spaces within SFR location are reserved and cannot be accessed by users.

The special page vectors are allocated addresses $FFE00_{16}$ to $FFFDB_{16}$. They are used for the JMPS instruction and JSRS instruction. Refer to the Renesas publication **M16C/60 and M16C/20 Series Software Manual** for details.

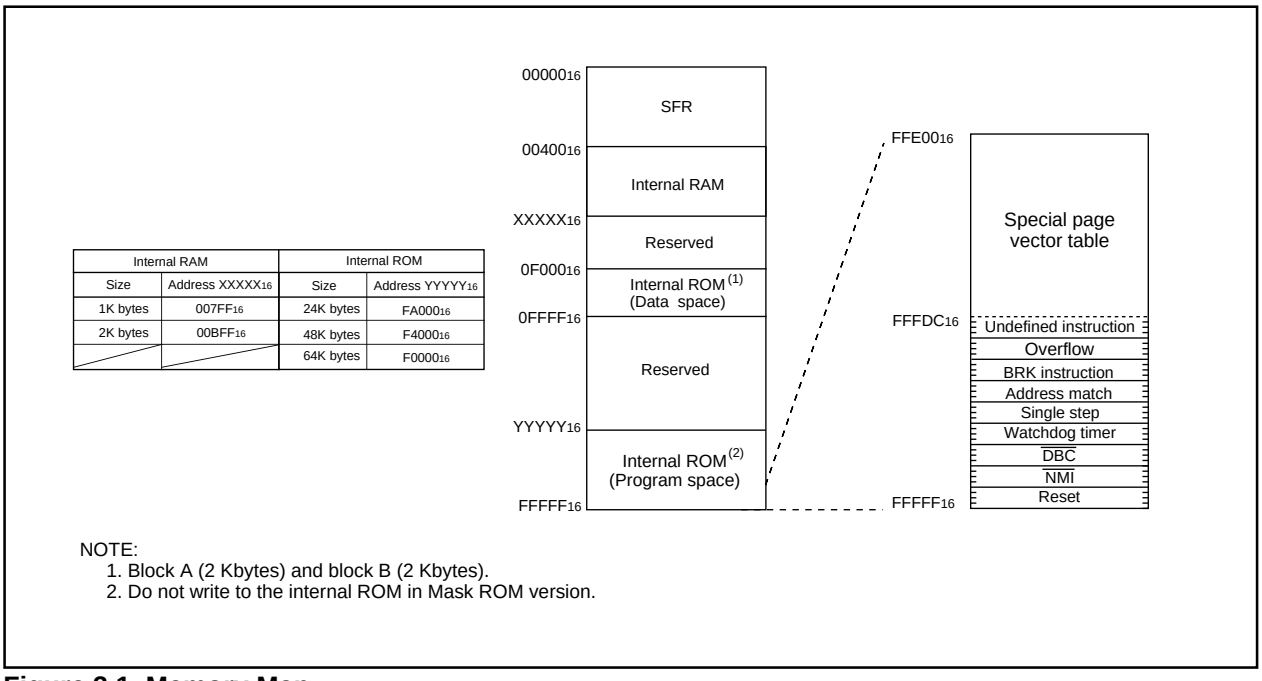


Figure 3.1 Memory Map

Table 4.4 SFR Information(4)(1)

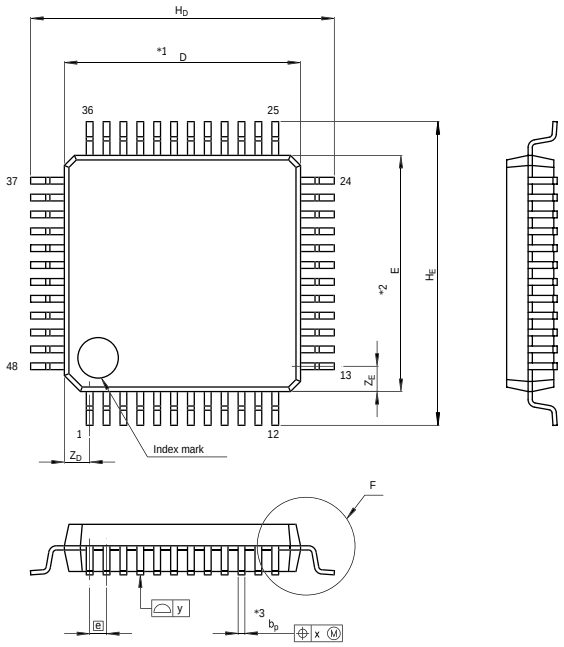
Address	Register	Symbol	After reset
034016			
034116			
034216	Timer A1-1 register	TA11	XX16
034316			XX16
034416	Timer A2-1 register	TA21	XX16
034516			XX16
034616	Timer A4-1 register	TA41	XX16
034716			XX16
034816	Three phase PWM control register 0	INVC0	0016
034916	Three phase PWM control register 1	INVC1	0016
034A16	Three phase output buffer register 0	IDB0	3F16
034B16	Three phase output buffer register 1	IDB1	3F16
034C16	Dead time timer	DTT	XX16
034D16	Timer B2 Interrupt occurrence frequency set counter	ICTB2	XX16
034E16	Position-data-retain function control register	PDRF	XXXX00002
034F16			
035016			
035116			
035216			
035316			
035416			
035516			
035616			
035716			
035816	Port function control register	PFCR	001111112
035916			
035A16			
035B16			
035C16			
035D16			
035E16	Interrupt request cause select register 2	IFSR2A	XXXXXXX02
035F16	Interrupt request cause select register	IFSR	0016
036016			
036116			
036216			
036316			
036416			
036516			
036616			
036716			
036816			
036916			
036A16			
036B16			
036C16			
036D16			
036E16			
036F16			
037016			
037116			
037216			
037316			
037416	UART2 special mode register 4	U2SMR4	0016
037516	UART2 special mode register 3	U2SMR3	000X0X0X2
037616	UART2 special mode register 2	U2SMR2	X00000002
037716	UART2 special mode register	U2SMR	X00000002
037816	UART2 transmit/receive mode register	U2MR	0016
037916	UART2 bit rate register	U2BRG	XX16
037A16	UART2 transmit buffer register	U2TB	XXXXXXXX2
037B16			XXXXXXXX2
037C16	UART2 transmit/receive control register 0	U2C0	000010002
037D16	UART2 transmit/receive control register 1	U2C1	000000102
037E16	UART2 receive buffer register	U2RB	XXXXXXXX2
037F16			XXXXXXXX2

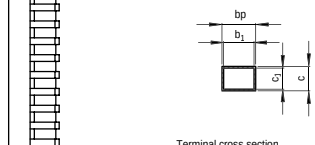
NOTE:
1. Blank spaces are reserved. No access is allowed.

X : Undefined

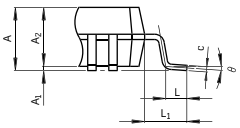
Package

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP48-7x7-0.50	PLQP0048KB-A	48P6Q-A	0.2g





Terminal cross section

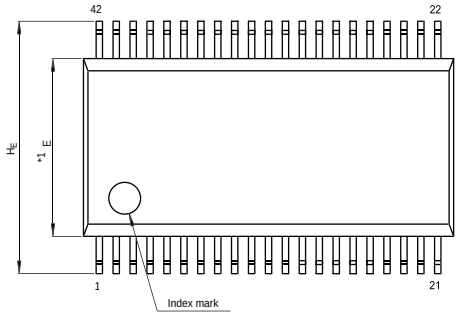


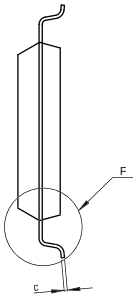
Detail F

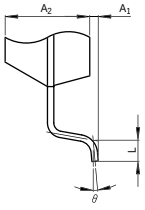
NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	6.9	7.0	7.1
E	6.9	7.0	7.1
A_2	—	1.4	—
H_D	8.8	9.0	9.2
H_E	8.8	9.0	9.2
A	—	—	1.7
A_1	0	0.1	0.2
b_p	0.17	0.22	0.27
b_1	—	0.20	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.10
Z_D	—	0.75	—
Z_E	—	0.75	—
L	0.35	0.5	0.65
L_1	—	1.0	—

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SSOP42-8.4x17.5-0.80	PRSP0042GA-B	42P2R-E	0.6g







Detail F

NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	17.3	17.5	17.7
E	8.2	8.4	8.6
A_2	—	2.0	—
A	—	—	2.4
A_1	0.05	—	—
b_p	0.25	0.3	0.4
c	0.13	0.15	0.2
θ	0°	—	10°
H_E	11.63	11.93	12.23
e	0.65	0.8	0.95
y	—	—	0.15
L	0.3	0.5	0.7

REVISION HISTORY	M16C/26A Group (M16C/26A, M16C/26B, M16C/26T) Shortsheet

Rev.	Date	Description	
		Page	Summary
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